



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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PRODUCT NUMBER
93696-YXXLF

- RoHS COMPATIBLE, SEE NOTE 6
- NUMBER OF POSITIONS PER ROW: 03 TO 50.
- PLATING CODE
 - 3= 0.76µm GOLD ON CONTACT AREA.
2µm MIN MATTE TIN ON TAIL.
 - 4= 2µm MIN MATTE TIN FULL PLATED
 - 1.27µm Ni MIN UNDERPLATING

NOTES:

- 1 - HOUSING MAT'L: THERMOPLASTIC GLASS FILLED
FLAME RETARDANT PER UL 94 V-0 COLOR: GREY.
- 2 - TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 - 3 UP TO 50 POSITIONS PRODUCT PACKED IN TUBE.
- 4 - TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
EXAMPLE: 8 POS: $((N+2) \times 2.54) - 0.08 = 25.32$ mm.
- 5 - $\phi 2.65$ MINI FOR ASSEMBLY WITHOUT INSERTION EFFORT.
- 6 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.

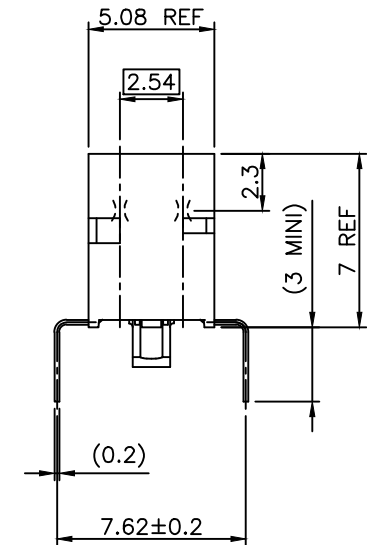
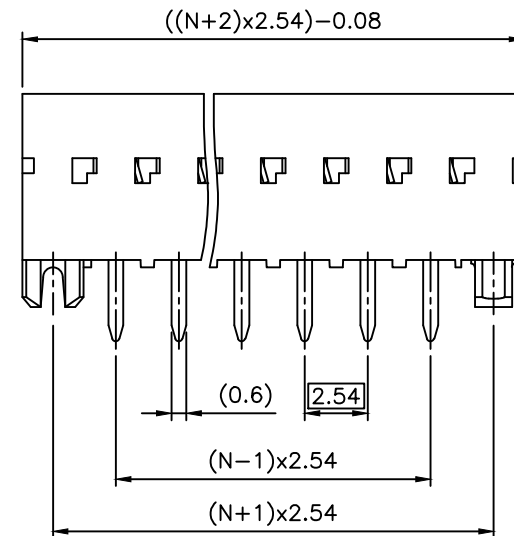
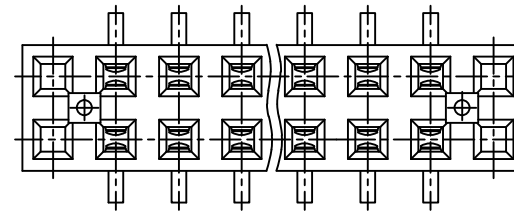
b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C $\pm 5^\circ$ C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELING:

- MEETS PACKAGING SPECS AS PER GS-14-920

d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code SEE NOTES		surface ISO 1302 <input checked="" type="checkbox"/> ISO 406 ISO 1101		tolerance ISO 406 ISO 1101		projection 		product family DUBOX	
ltr	ecn no	dr	date	tolerances unless otherwise specified		mm		title	
L	F06-0204	DLE	06.06.28	angles	linear	mm		BtB RECEPT.	
M	F06-0323	DLE	06.11.21	±2'		scale 5:1		VERT DR TMT	
N	B-19124	LMU	14.10.21	dr	P.NIZZI	95.09.20	dwg no		sheet 1 of 2
H	F10116	GCO	01.01.23	enrg	JM.PHAMVAN	95.09.20	93696		A3
J	F04-0347	DLE	04.11.15	chr	P.NIZZI	95.09.20	type		CUSTOMER Drawing
K	F06-0137	DLE	06.02.27	appd	JM.P	95.09.20			
sheet	revision	N	B						
index	sheet	1	2						



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